onsemi

MOSFET - SiC Power, Single N-Channel, TO247-3L

650 V, 57 mΩ, 38 A

NVHL075N065SC1

Features

- Typ. $R_{DS(on)} = 57 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$ Typ. $R_{DS(on)} = 75 \text{ m}\Omega @ V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge ($Q_{G(tot)} = 61 \text{ nC}$)
- Low Output Capacitance (Coss = 107 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

Typical Applications

- Automotive On Board Charger
- Automotive DC/DC Converter for EV/HEV

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Baram	Symbol	Value	Unit		
Parameter			Symbol	value	
Drain-to-Source Voltage			V _{DSS}	650	V
Gate-to-Source Voltage			V _{GS}	-8/+22	V
Recommended Operation Values T _C < 175°C of Gate-to-Source Voltage		V _{GSop}	-5/+18	V	
Continuous Drain Current (Note 1)	Steady State	$T_C = 25^{\circ}C$	۱ _D	38	A
Power Dissipation (Note 1)			P _D	148	W
Continuous Drain Current (Note 1)	Steady State	T _C = 100°C	۱ _D	26	А
Power Dissipation (Note 1)			P _D	74	W
Pulsed Drain Current (Note 2)	$T_{C} = 25^{\circ}C$		I _{DM}	120	A
Operating Junction and Storage Temperature Range			T _J , T _{stg}	–55 to +175	°C
Source Current (Body Diode)			۱ _S	34	А
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)}$ = 12.9 A, L = 1 mH) (Note 3)			E _{AS}	83	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			ΤL	260	°C

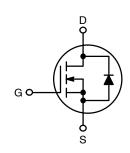
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

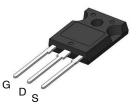
1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Repetitive rating, limited by max junction temperature.

3. EAS of 83 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 12.9 A, V_{DD} = 50 V, V_{GS} = 18 V.

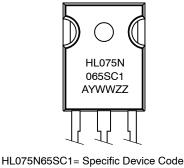
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
650 V	85 mΩ @ 18 V	38 A	





TO-247 Long Leads CASE 340CX

MARKING DIAGRAM



= Assembly Location

А

YWW	= Data Code (Year & Week)
ZZ	= Assembly Lot

ORDERING INFORMATION

Device	Package	Shipping		
NVHL075N065SC1	TO247-3L	30 Units / Tube		

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 1)	$R_{\theta JC}$	1.01	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA		650	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	$I_D = 20$ mA, referenced to $25^{\circ}C$		-	0.15	-	V/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	$T_J = 25^{\circ}C$	-	-	10	μA
		V _{DS} = 650 V T _J = 175°C		-	-	1	mA
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = +18/-5$ V,	V _{DS} = 0 V	-	-	250	nA
ON CHARACTERISTICS (Note 2)		-					-
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 5 mA	1.8	2.8	4.3	V
Recommended Gate Voltage	V _{GOP}			-5	-	+18	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 15 .	A, T _J = 25°C	-	75	-	mΩ
		V _{GS} = 18 V, I _D = 15	A, T _J = 25°C	-	57	85	
		V _{GS} = 18 V, I _D = 15 A	A, T _J = 175°C	-	68	-	
Forward Transconductance	9 _{FS}	V _{DS} = 10 V, I _D	= 15 A	-	9	_	S
CHARGES, CAPACITANCES & GATE RES	ISTANCE	1					
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 325 V		-	1196	_	pF
Output Capacitance	C _{OSS}			-	107	-	
Reverse Transfer Capacitance	C _{RSS}			-	9	-	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/18 \text{ V}, V_{DS} = 520 \text{ V},$ $I_D = 15 \text{ A}$		-	61	-	nC
Gate-to-Source Charge	Q _{GS}			-	19	-	
Gate-to-Drain Charge	Q _{GD}			-	18	-	
Gate-Resistance	R _G	f = 1 MHz		-	5.8	-	Ω
SWITCHING CHARACTERISTICS		1					
Turn-On Delay Time	t _{d(ON)}	V _{GS} = -5/18 V,		-	10	_	ns
Rise Time	t _r	V _{DS} = 400 I _D = 15 A		-	26	-	1
Turn–Off Delay Time	t _{d(OFF)}	R _G = 2.2	$\overline{R_G} = 2.2 \Omega$		22	-	
Fall Time	t _f	inductive load		-	8	-	
Turn-On Switching Loss	E _{ON}			-	113	-	μJ
Turn-Off Switching Loss	E _{OFF}			-	16	-	
Total Switching Loss	E _{tot}			-	129	_	
DRAIN-SOURCE DIODE CHARACTERIST		1			1		
Continuous Drain-Source Diode Forward Current	I _{SD}	V_{GS} = -5 V, T_{J} = 25°C		_	-	34	A
Pulsed Drain-Source Diode Forward Current (Note 2)	I _{SDM}			-	-	120	
	1			l			l

 V_{GS} = –5 V, I_{SD} = 15 A, T_J = 25°C

_

4.4

_

V

 V_{SD}

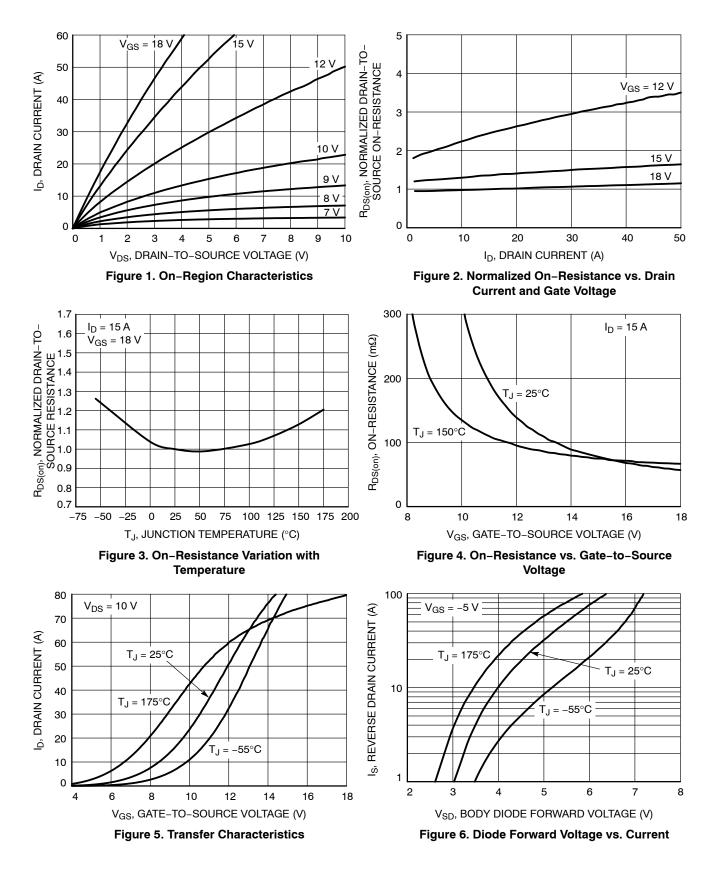
Forward Diode Voltage

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified) (continued)

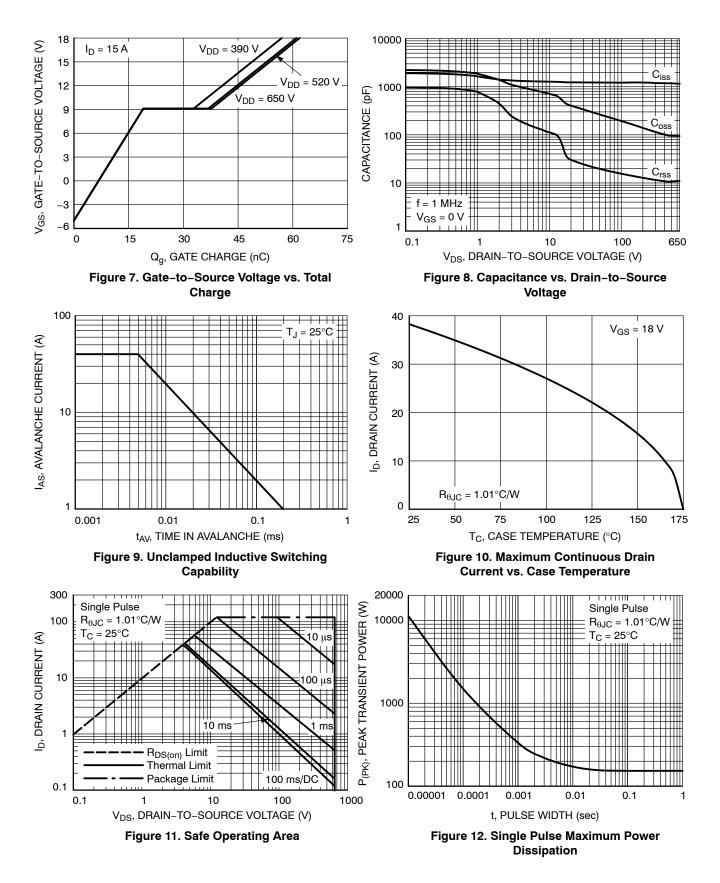
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Reverse Recovery Time	t _{RR}	V_{GS} = -5/18 V, I _{SD} = 15 A, dI _S /dt = 1000 A/µs	-	16	-	ns	
Reverse Recovery Charge	Q _{RR}	ai _S /at = 1000 A/µs	-	68	-	nC	
Reverse Recovery Energy	E _{REC}		-	11	-	μJ	
Peak Reverse Recovery Current	I _{RRM}		-	8.7	-	А	
Charge time	Та]	-	8.4	-	ns	
Discharge time	Tb]	-	7.4	-	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



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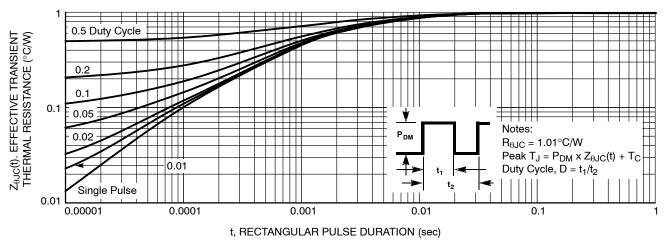
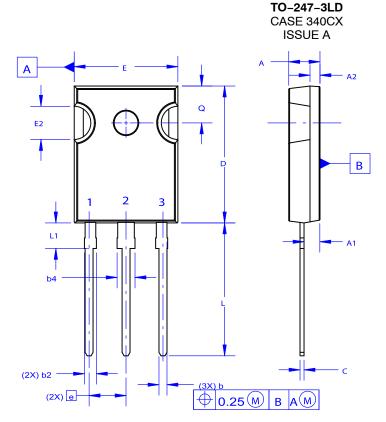


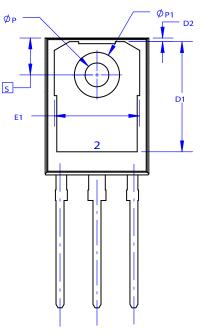
Figure 13. Junction-to-Case Thermal Response

PACKAGE DIMENSIONS



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



	MILLIMETERS					
DIM	MIN	NOM	MAX			
A	4.58	4.70	4.82			
A1	2.20	2.40	2.60			
A2	1.40	1.50	1.60			
D	20.32	20.57	20.82			
E	15.37	15.62	15.87			
E2	4.96	5.08	5.20			
е	~	5.56	~			
L	19.75	20.00	20.25			
L1	3.69	3.81	3.93			
ØР	3.51	3.58	3.65			
Q	5.34	5.46	5.58			
S	5.34	5.46	5.58			
b	1.17	1.26	1.35			
b2	1.53	1.65	1.77			
b4	2.42	2.54	2.66			
С	0.51	0.61	0.71			
D1	13.08	~	~			
D2	0.51	0.93	1.35			
E1	12.81	~	~			
ØP1	6.60	6.80	7.00			

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